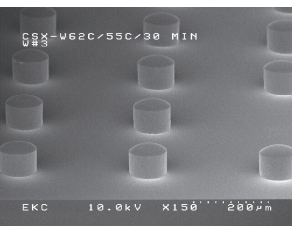


EKC Technology

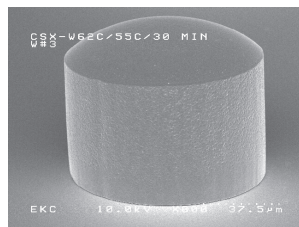
Wafer Level Packaging Photoresist Remover

For Complete Resist Removal

DuPont™ WBR Series Dry Film



Before PR removal

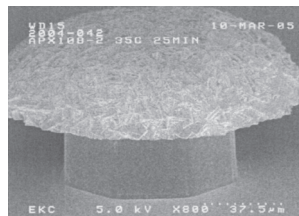


After PR removal

Liquid Resist



Before PR removal



After PR removal

Product Description

WLP EKC162™ is a formulation optimized to effectively remove thick and thin negative resists used for TSV masks and wafer bumping by solder electroplating or stencil printing. The product is designed for use in spray processing equipment and wet benches.

Features

- Formulated to give complete resist removal and eliminate resist re-deposit
- Short stripping time
- High wafer capacity with long bathlife
- Compatible with wet bench and spray process equipment
- Operates at moderate temperatures
- Low evaporation rate at operating temperature
- Completely water rinsable
- High flashpoint
- Compatible with copper and a wide variety of Under Bump Metallization
- Compatible with conventional and lead free solder

Benefits

- No polymer residues around bumps
- Eliminates UBM etch masking
- Offers flexibility in equipment choice
- Higher throughput
- Resource conservation through reduced stripping time and temperature
- Reduced material use and disposal from less frequent bath or tank changes
- Lower overall operating costs



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For more information on Wafer Level Packaging Photoresist Remover or other DuPont Semiconductor Materials Solutions, please contact your local representative:

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